

## P-Channel Enhancement Mode MOSFET

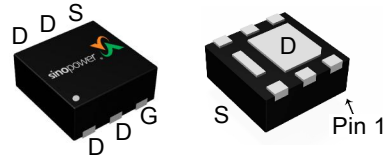
### Features

- 12V/-11A,  
 $R_{DS(ON)} = 13.8m\Omega(max.) @ V_{GS} = -4.5V$   
 $R_{DS(ON)} = 19m\Omega(max.) @ V_{GS} = -2.5V$   
 $R_{DS(ON)} = 26m\Omega(max.) @ V_{GS} = -1.8V$   
 $R_{DS(ON)} = 36m\Omega(max.) @ V_{GS} = -1.5V$
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

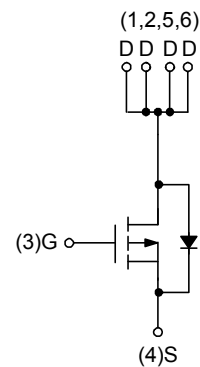
### Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

### Pin Description



DFN2x2-6



P-Channel MOSFET

### Ordering and Marking Information

<p>SM2223PS □□□-□□□</p> <div style="margin-left: 40px;"> <p>└─ Assembly Material</p> <p>└─ Handling Code</p> <p>└─ Temperature Range</p> <p>└─ Package Code</p> </div>	<p>Package Code QG : DFN2x2-6</p> <p>Operating Junction Temperature Range C : -55 to 150 °C</p> <p>Handling Code TR : Tape &amp; Reel (3000ea/reel)</p> <p>Assembly Material G : Halogen and Lead Free Device</p>
<p>SM2223PS QG : <span style="border: 1px solid black; padding: 2px;">2223 BXXX</span></p>	<p>XXX - Lot Code</p>

Note : SINOPOWER lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. SINOPOWER lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. SINOPOWER defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

SINOPOWER reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

## Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit	
$V_{DSS}$	Drain-Source Voltage	-12	V	
$V_{GSS}$	Gate-Source Voltage	$\pm 8$		
$I_D^a$	Continuous Drain Current ( $V_{GS}=-4.5V$ )	$T_A=25^\circ\text{C}$	-11	A
		$T_A=70^\circ\text{C}$	-8.8	
$I_{DM}^a$	Pulsed Drain Current ( $V_{GS}=-4.5V$ )	-44 *		
$I_S^a$	Diode Continuous Forward Current	-3		
$I_{AS}^c$	Avalanche Current, Single pulse	L=0.1mH	28	A
		L=0.5mH	16	
$E_{AS}^c$	Avalanche Energy, Single pulse	L=0.1mH	39	mJ
		L=0.5mH	64	
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$	
$T_{STG}$	Storage Temperature Range	-55 to 150		
$P_D^a$	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	2.5	W
		$T_A=70^\circ\text{C}$	1.6	
$R_{\theta JA}^{a,b}$	Thermal Resistance-Junction to Ambient	$t \leq 10s$	50	$^\circ\text{C/W}$
		Steady State	80	

Note \* : Current limited by bond wire.

Note a : Surface Mounted on  $1\text{in}^2$  pad area,  $t \leq 10\text{sec}$ .

Note b : Maximum under Steady State conditions is  $75^\circ\text{C/W}$ .

Note c : UIS tested and pulse width limited by maximum junction temperature  $150^\circ\text{C}$  (initial temperature  $T_J=25^\circ\text{C}$ ).

## Electrical Characteristics (T<sub>A</sub> = 25°C Unless Otherwise Noted)

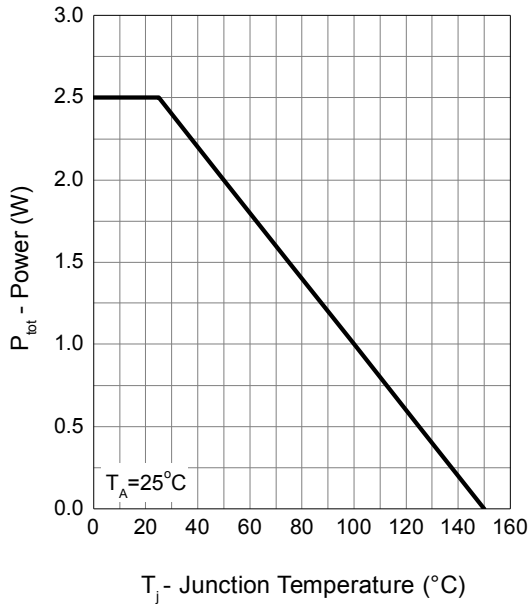
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =-250μA	-12	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-9.6V, V <sub>GS</sub> =0V	-	-	-1	μA
		T <sub>J</sub> =85°C	-	-	-30	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =-250μA	-0.4	-	-0.9	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V	-	-	±100	nA
R <sub>DS(ON)</sub> <sup>d</sup>	Drain-Source On-state Resistance	V <sub>GS</sub> =-4.5V, I <sub>DS</sub> =-11A	-	11	13.8	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>DS</sub> =-7A	-	14	19	
		V <sub>GS</sub> =-1.8V, I <sub>DS</sub> =-5A	-	18	26	
		V <sub>GS</sub> =-1.5V, I <sub>DS</sub> =-3A	-	24	36	
<b>Diode Characteristics</b>						
V <sub>SD</sub> <sup>d</sup>	Diode Forward Voltage	I <sub>SD</sub> =-1A, V <sub>GS</sub> =0V	-	-0.7	-1	V
t <sub>rr</sub> <sup>e</sup>	Reverse Recovery Time	I <sub>F</sub> =-11A, dI <sub>SD</sub> /dt=100A/μs	-	35	-	ns
Q <sub>rr</sub> <sup>e</sup>	Reverse Recovery Charge		-	19	-	nC
<b>Dynamic Characteristics<sup>e</sup></b>						
R <sub>g</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	-	1.7	-	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-6V, Frequency=1.0MHz	-	2100	-	pF
C <sub>oss</sub>	Output Capacitance		-	612	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	500	-	
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-10V, R <sub>L</sub> =10Ω, I <sub>DS</sub> =-1A, V <sub>GEN</sub> =-4.5V, R <sub>G</sub> =6Ω	-	12	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	14	-	
t <sub>d(OFF)</sub>	Turn-off Delay Time		-	80	-	
t <sub>f</sub>	Turn-off Fall Time		-	50	-	
<b>Gate Charge Characteristics<sup>e</sup></b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-6V, V <sub>GS</sub> =-4.5V, I <sub>DS</sub> =-11A	-	25	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	2.8	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	8	-	

Note d : Pulse test ; pulse width≤300μs, duty cycle≤2%.

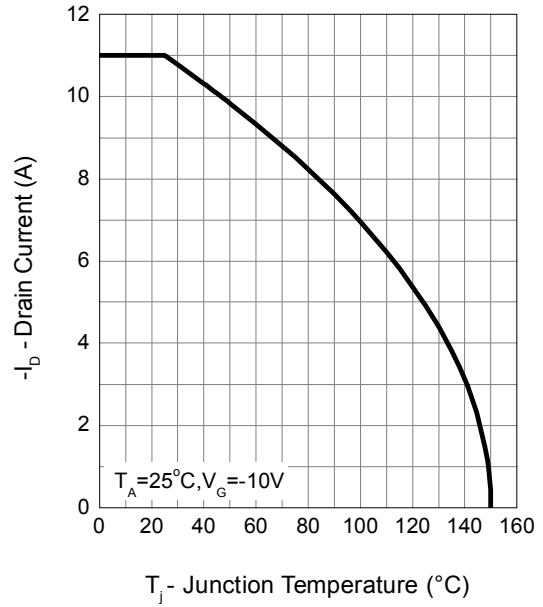
Note e : Guaranteed by design, not subject to production testing.

## Typical Operating Characteristics

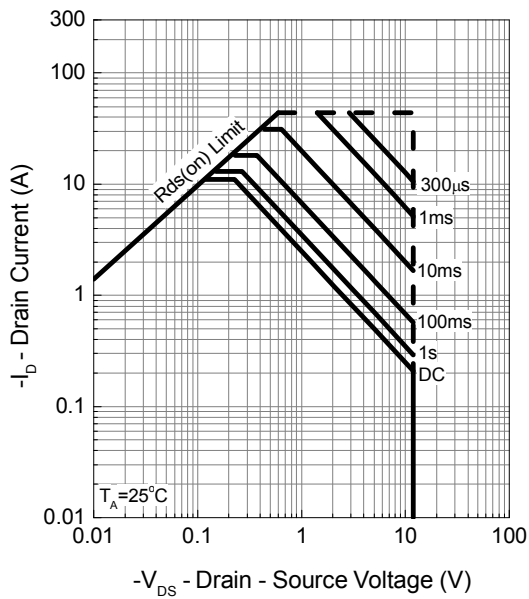
Power Dissipation



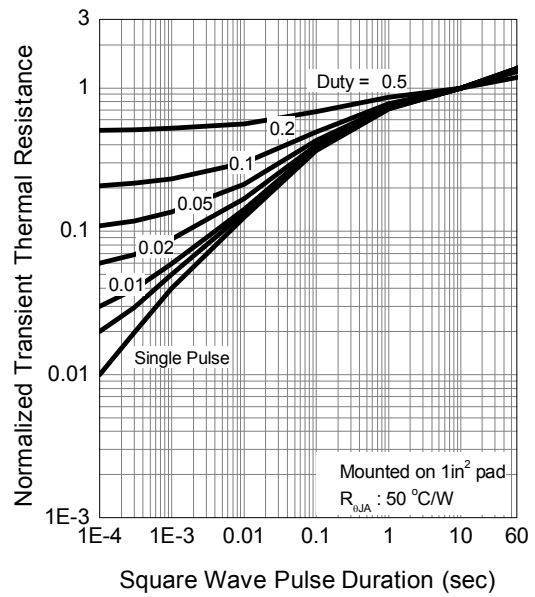
Drain Current



Safe Operation Area

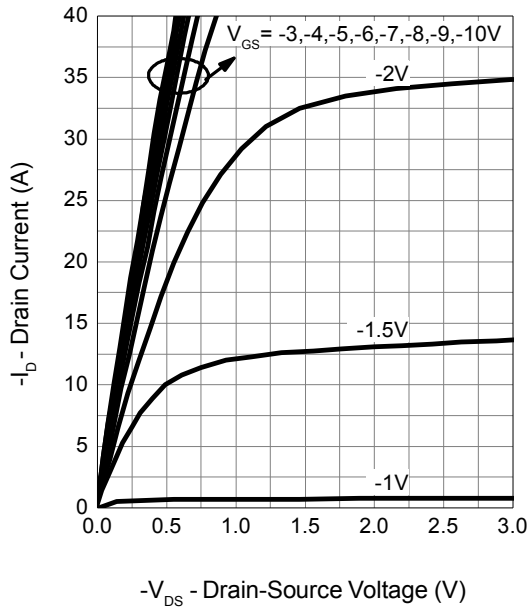


Thermal Transient Impedance

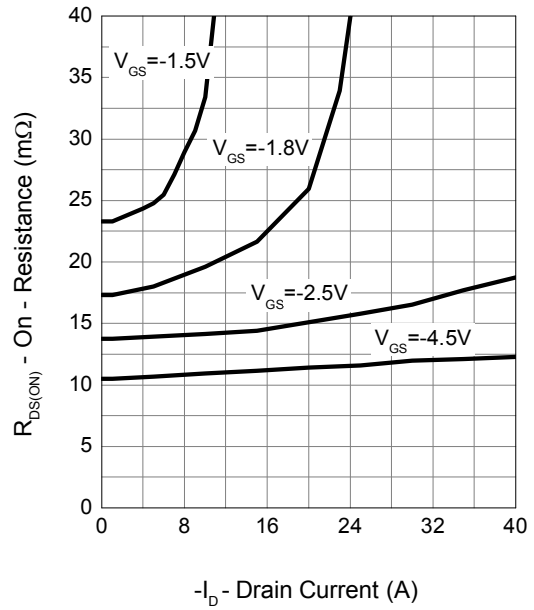


## Typical Operating Characteristics (Cont.)

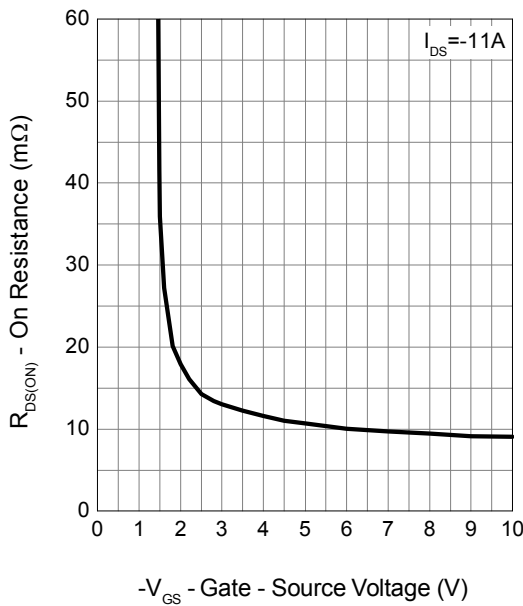
Output Characteristics



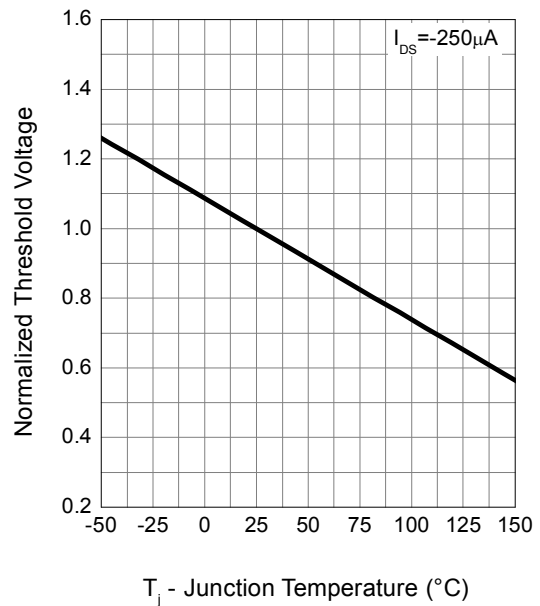
Drain-Source On Resistance



Gate-Source On Resistance

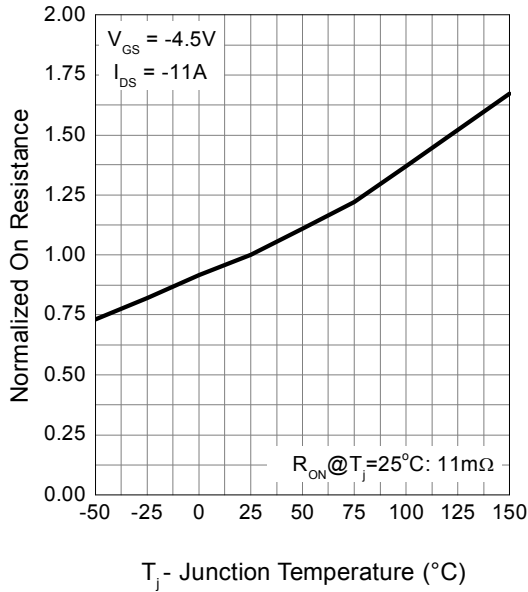


Gate Threshold Voltage

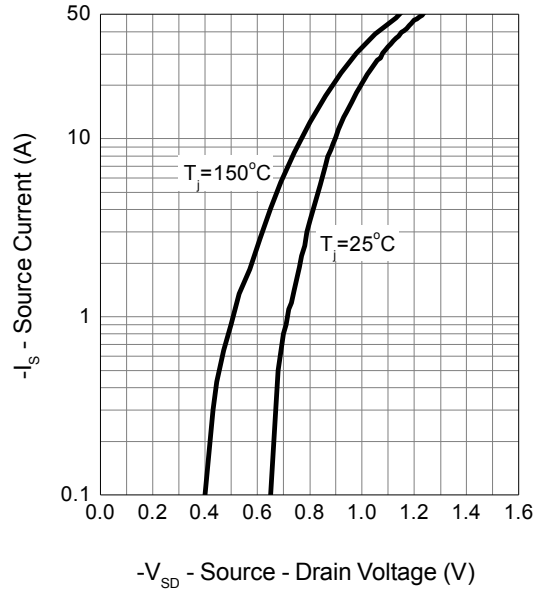


Typical Operating Characteristics (Cont.)

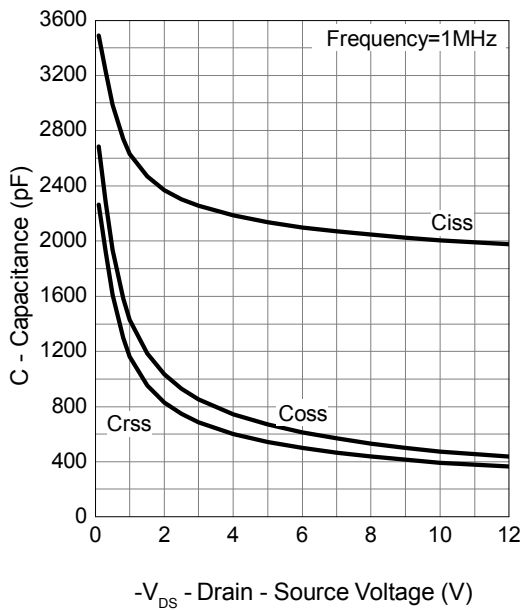
Drain-Source On Resistance



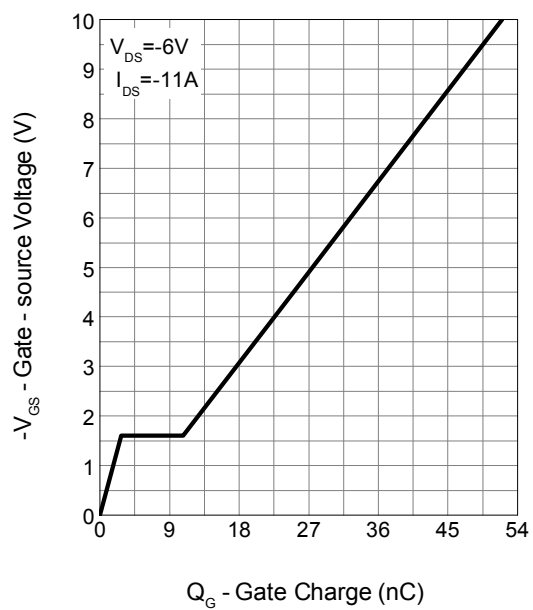
Source-Drain Diode Forward



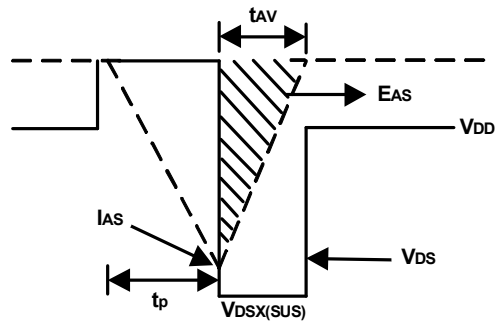
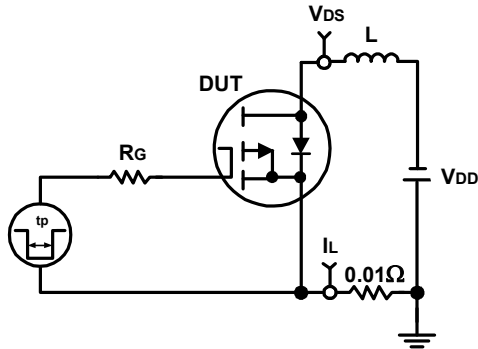
Capacitance



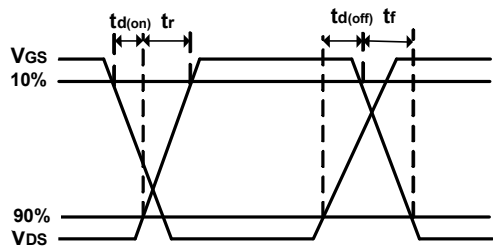
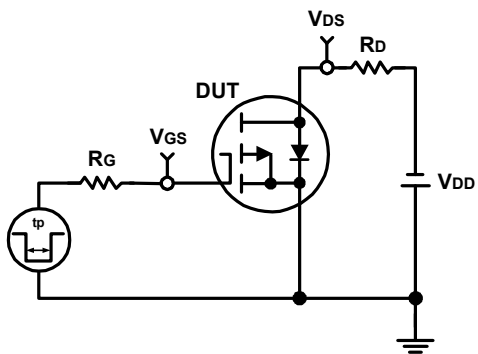
Gate Charge



### Avalanche Test Circuit and Waveforms

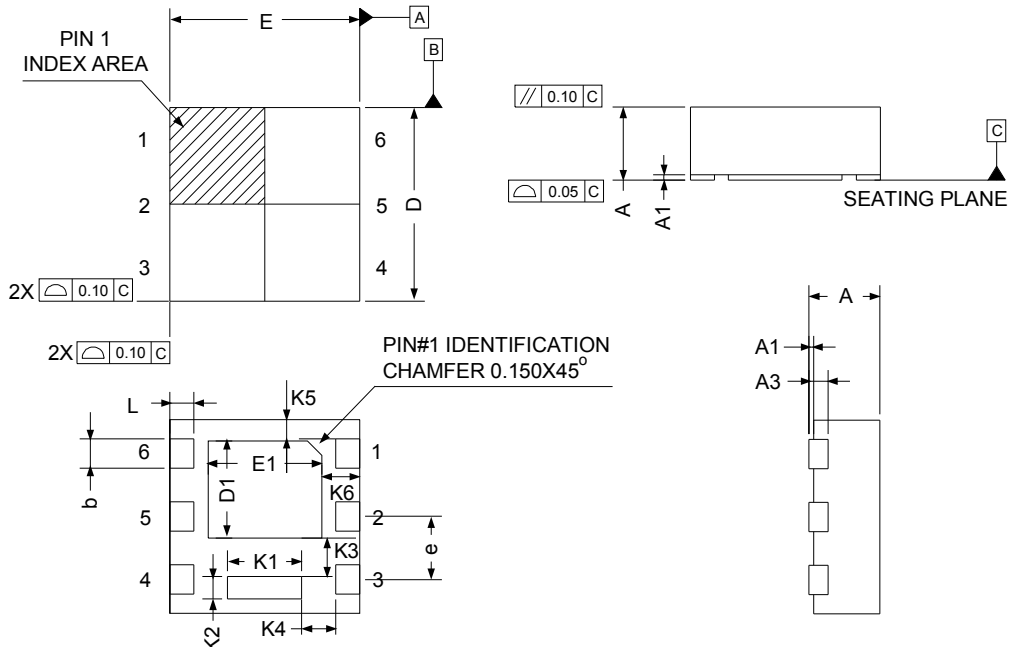


### Switching Time Test Circuit and Waveforms



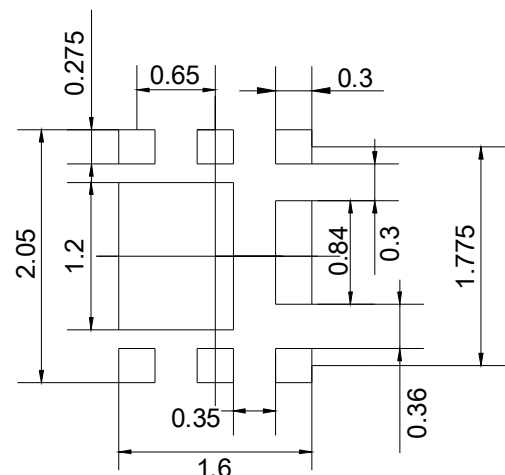
## Package Information

DFN2x2-6



SYMBOL	DFN2x2-6			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	0.80	0.028	0.031
A1	0.00	0.05	0.000	0.002
A3	0.200 REF		0.008 REF	
b	0.25	0.35	0.010	0.014
D	1.90	2.10	0.075	0.083
E	1.90	2.10	0.075	0.083
D1	0.90	1.10	0.035	0.043
E1	0.90	1.10	0.035	0.043
e	0.65 BSC		0.026 BSC	
L	0.20	0.30	0.008	0.012
K1	0.65	0.85	0.026	0.033
K2	0.20	-	0.008	-
K3	0.20	-	0.008	-
K4	0.32	-	0.013	-
K5	0.20	0.26	0.008	0.010
K6	0.45	0.55	0.018	0.022

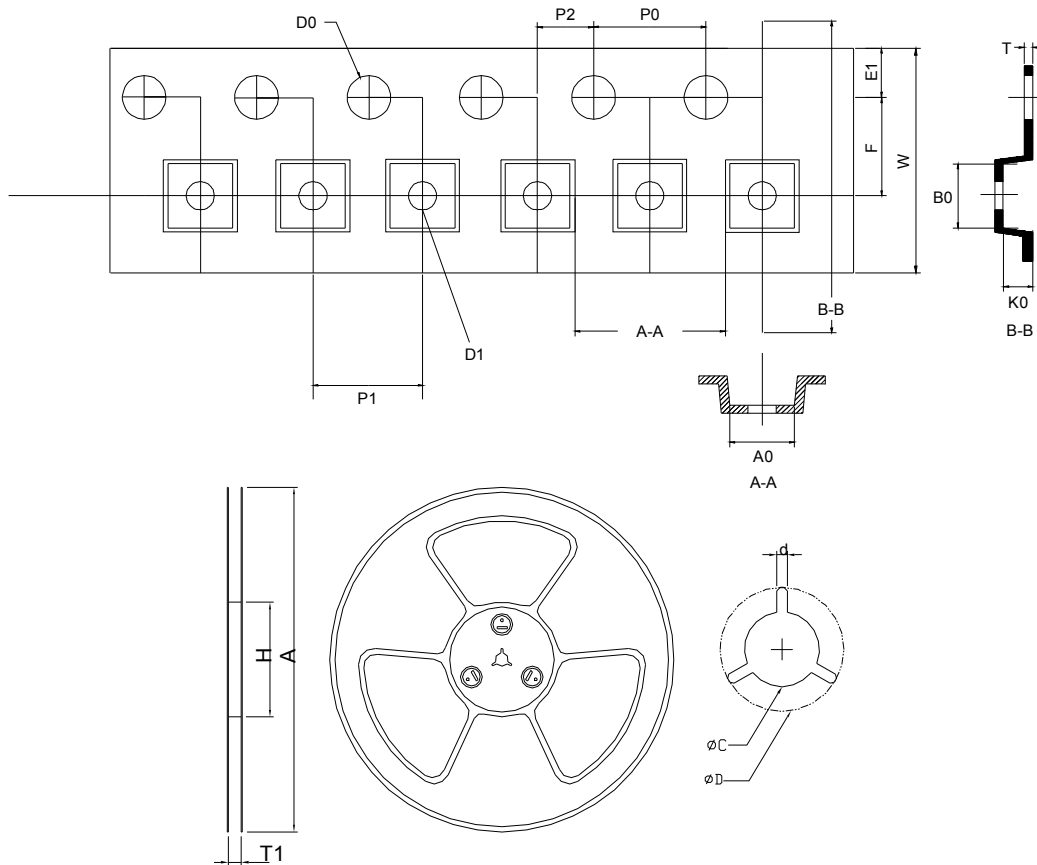
### RECOMMENDED LAND PATTERN



UNIT: mm



## Carrier Tape & Reel Dimensions

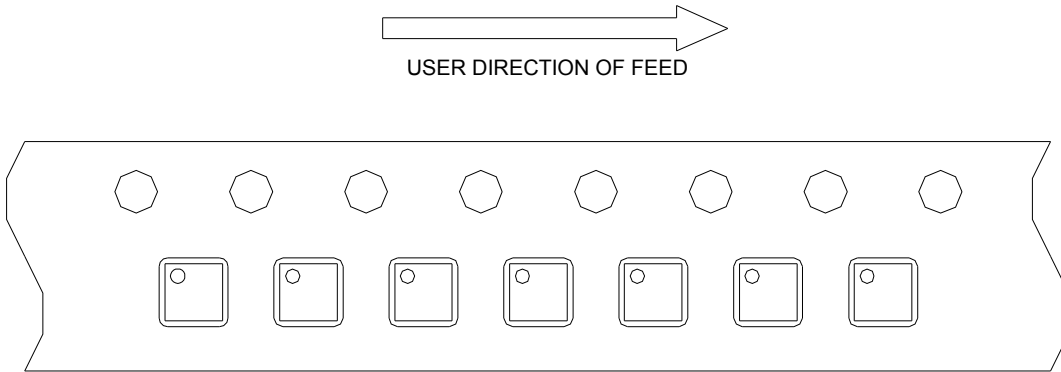


Application	A	H	T1	C	d	D	W	E1	F
DFN2x2-6	178.0±2.00	60.0±0.50	9.0±2.00	13.0+0.50 -0.20	2.0±0.20	21.0±0.50	8.0+0.30 -0.10	1.75±0.10	3.5±0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0±0.10	4.0±0.10	2.0±0.05	1.5+0.10 -0.00	1.0 MIN.	0.3±0.05	2.3±0.10	2.3±0.10	1.05±0.10

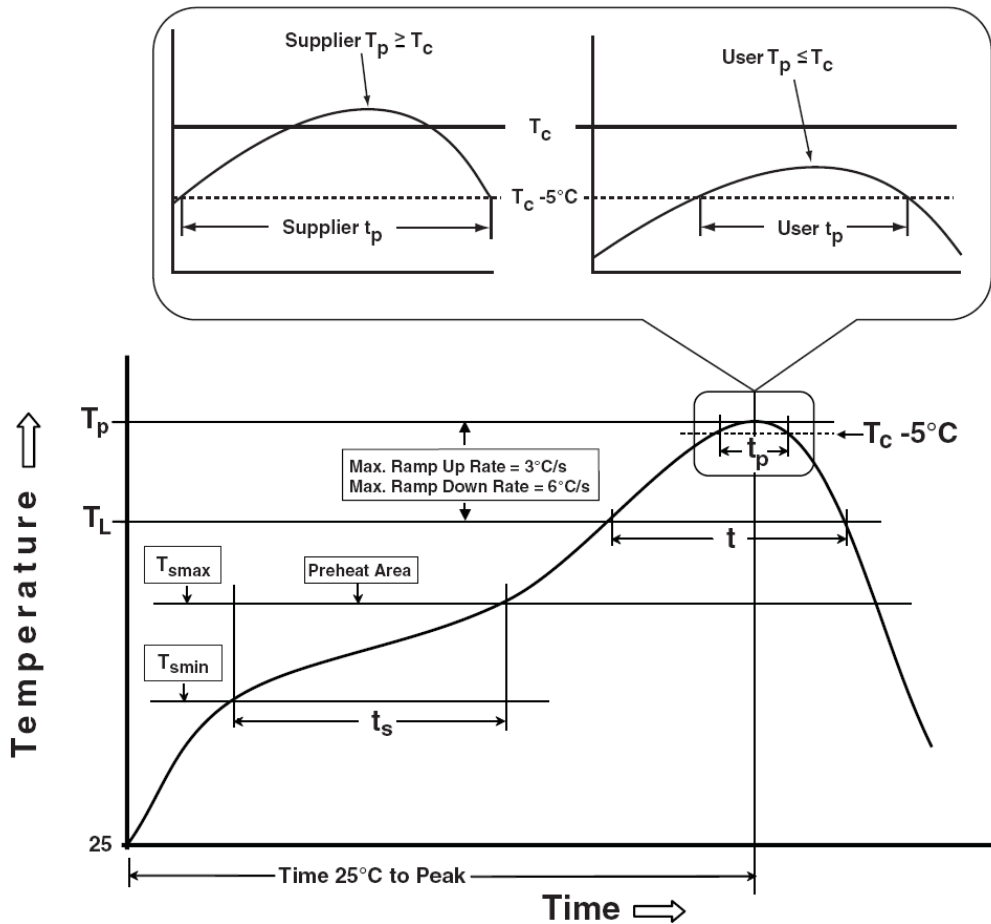
(mm)

## Taping Direction Information

DFN2x2-6



## Classification Profile



## Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_L$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ $T_{jmax}$
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ $T_{jmax}$
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

## Customer Service

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